

**IN THE CLAIMS:**

Please add new claims 10-20, and amend the claims as follows:

1. (Currently Amended) An electro-chemical deposition system, comprising:
  - a) a mainframe having a mainframe wafer transfer robot;
  - b) a loading station disposed in connection with the mainframe;
  - c) one or more processing cells disposed in connection with the mainframe;
  - d) an electrolyte supply fluidly connected to the one or more electrical processing cells; and
  - e) ~~a spin-rinse-dry (SRD) chamber disposed between the loading station and the mainframe; and~~ f) a thermal anneal chamber disposed adjacent the loading station.
2. (Original) The system of claim 1 wherein the thermal anneal chamber comprises a rapid thermal anneal chamber having a heater plate.
3. (Original) The system of claim 2 wherein the heater plate comprises an atmospheric pressure heater plate.
4. (Currently Amended) The system of claim 1, further comprising:
  - e) ~~f)~~ a system controller adapted to control operations of one or more components of the electro-chemical deposition system.
5. (Original) The system of claim 4, wherein the thermal anneal chamber further comprises a gas inlet adapted to introduce one or more gases into the thermal anneal chamber.
6. (Original) The system of claim 5 wherein the system controller controls the gas inlet to the chamber to provide a chamber environment having an oxygen content of less than 100 parts per million.

7. (Original) The system of claim 6 wherein the gas inlet is connected to a nitrogen gas source to introduce nitrogen into the chamber.
8. (Original) The system of claim 6 wherein the gas inlet is connected to a nitrogen gas source and a hydrogen gas source to introduce nitrogen and hydrogen into the chamber, wherein the hydrogen content is maintained at less than about 4%.
9. (Currently Amended) The system of claim 1 wherein the loading station comprises:
- i) one or more wafer cassette receiving areas;
  - ii) one or more loading station wafer transfer robots for transferring a wafer ~~between the loading station and the SRD station and between the loading station and the thermal anneal chamber;~~ and
  - iii) a wafer orientor.
10. (New) An electro-chemical deposition system, comprising:
- a mainframe having a mainframe wafer transfer robot disposed therein;
  - a loading station disposed in connection with the mainframe, wherein the loading station comprises one or more loading station robots;
  - one or more processing stations disposed in connection with the mainframe, wherein each processing station comprises one or more electrochemical deposition cells; and
  - one or more post deposition treatment chambers disposed in connection with the mainframe.
11. (New) The deposition system of claim 10, wherein the loading station further comprises one or more cassette receiving areas and at least one wafer orientor.
12. (New) The deposition system of claim 10, wherein the one or more post deposition treatment chambers comprise one or more spin-rinse-dry modules and

wherein the one or more loading station robots transfer wafers between the one or more cassette receiving areas and the one or more spin-rinse-dry modules.

13. (New) The deposition system of claim 12, wherein the one or more spin-rinse-dry modules are connected between the loading station and the mainframe.

14. (New) The deposition system of claim 10, wherein at least one of the mainframe wafer transfer robots facilitates transfer of a wafer from a face-up position to a face-down position.

15. (New) The deposition system of claim 10, wherein the one or more post deposition treatment chambers comprise one or more rapid thermal anneal chambers, one or more thermal anneal chambers, or a combination thereof.

16. (New) The deposition system of claim 10, further comprising an electrolyte replenishing system disposed about the mainframe in fluid communication with each of the electrochemical deposition cells.

17. (New) An electro-chemical deposition system, comprising:  
a mainframe having a mainframe wafer transfer robots disposed therein;  
a loading station disposed in connection with the mainframe, wherein the loading station comprises one or more cassette receiving areas;  
two or more processing stations disposed in connection with the mainframe, wherein each processing station comprises two or more electrochemical deposition cells; and  
two or more post deposition treatment chambers in connection with the loading station.

18. (New) The deposition system of claim 17, wherein the two or more post deposition treatment chambers comprise two or more spin-rinse-dry modules.

19. (New) The deposition system of claim 18, wherein the one or more loading station robots transfer wafers between the one or more cassette receiving areas and the two or more post deposition treatment chambers.

20. (New) The deposition system of claim 19, wherein the two or more post deposition treatment chambers comprises one or more thermal anneal chambers.